

ABSTRACT

A method for packaging a multi-chip module includes the steps of: connecting connection terminals of a tape of an anisotropic conductive adhesive film, on which a circuit is patterned to bond pads of the chip by applying an adhesive on the tape, applying an adhesive on an upper surface of the chip, folding the tape and attaching the folded tape to the upper surface of the chip and forming a plurality of ball terminals on a lower surface of the tape, the ball terminals being electrically connected to the connection terminals of the tape. An individual chip scale package may be manufactured by repeating the above steps.